

FORM PTO-1449

Docket Number (Optional)

Application Number

341.6910USU

09/845,549

Applicant

Pasqualoni et al.

Filing Date

April 30, 2001

Group Art Unit

3723

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
/	3,170,273	2/23/65	Walsh et al.			
/	3,527,028	9/26/67	Donald R. Oswald			
/	4,050,954	9/27/77	Jagtar S. Basi			
/	4,169,337	10/2/79	Charles C. Payne			
/	4,304,575	12/8/81	Charles C. Payne			
/	4,462,188	07/31/84	Charles C. Payne			
/	5,139,571	08/18/92	Deal et al.			
/	5,230,833	07/27/93	Romberger et al.			
/	5,246,624	9/21/93	Miller et al.			
/	5,314,843	05/24/94	Yu et al.			
/	5,340,370	08/23/94	Cadien et al.			

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AUG 3 2001

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FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

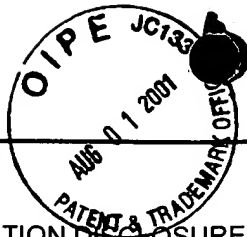
/	"Chemical-Mechanical Polishing of Copper in Glycerol Based Slurries" (Materials Research Society Symposium Proceedings, 1996), Kumar et al.; no month
/	"Chemical-Mechanical Polishing of Copper with Oxide and Polymer Interlevel Dielectrics" (Thin Solid Films, 1995), Gutman et al. no month
/	"Stabilization of Alumina Slurry for Chemical-Mechanical Polishing of Copper" (Langmuri, 1996) Lou et al. (no month)

EXAMINER

DATE CONSIDERED

12/9/02

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

Sheet 2 of 2

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	5,607,718	3/4/97	Sasaki et al.			
	5,656,097	8/12/97	Olesen et al.			
	5,695,384	12/9/97	Howard R. Beratan			
	5,750,440	5/12/98	Vanell et al.			
	5,770,095	6/23/98	Sasaki et al.			
	5,908,509	6/1/99	Olesen et al.			
	5,954,997	9/21/99	Kaufman et al.			
	5,980,775	11/9/99	Grumbine et al.			
	5,993,685	11/30/99	Currie et al.			
	5,996,595	12/7/99	Olesen et al.			
	6,010,962	1/4/00	Liu et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

	"Initial Study on Copper MCP Slurry Chemistries" (Thin Solid Films, 1995) Carpio et al. (no month)
	"Chemical-Mechanical Polishing of Copper for Interconnect Formation" (Microelectronic Engineering, 1997) Stavreva et al. (no month)
	"Development of a 1:1:1 Slurry for Tantalum Layer Polishing" in proceedings of the CMP-MIC conference, February 1999

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